

MOS FIELD EFFECT TRANSISTOR μ PA2707GR

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The μ PA2707GR is N-channel MOS Field Effect Transistor designed for DC/DC converter and power management applications of notebook computer.

FEATURES

• Low on-state resistance

 $R_{DS(on)1}$ = 4.3 m Ω MAX. (VGS = 10 V, ID = 9.0 A) $R_{DS(on)2}$ = 5.6 m Ω MAX. (VGS = 4.5 V, ID = 9.0 A)

- Low Ciss: Ciss = 6600 pF TYP. (VDS = 10 V, VGS = 0 V)
- Small and surface mount package (Power SOP8)

ORDERING INFORMATION

PART NUMBER	PACKAGE
μ PA2707GR-E1	Power SOP8
μ PA2707GR-E1-A Note	Power SOP8
μ PA2707GR-E2	Power SOP8
μ PA2707GR-E2-A Note	Power SOP8

Note Pb-free (This product does not contain Pb in external electrode and other parts.)

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, All terminals are connected.)

Drain to Source Voltage (V _{GS} = 0 V)	VDSS	30	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC)	ID(DC)	±19	Α
Drain Current (pulse) Note1	D(pulse)	±76	Α
Total Power Dissipation Note2	P _{T1}	1.1	W
Total Power Dissipation (PW = 10 sec) Note2	P _{T2}	2.5	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note3	las	19	Α
Single Avalanche Energy Note3	Eas	36	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

- 2. Mounted on glass epoxy board of 1 inch x 1 inch x 0.8 mm
- 3. Starting T_{ch} = 25°C, V_{DD} = 15 V, R_G = 25 Ω , L = 100 μ H, V_{GS} = 20 \rightarrow 0 V

THERMAL RESISTANCE

Channel to Ambient Note	Rth(ch-A)	114	°C/W
Channel to Drain Lead Note	Rth(ch-L)	22	°C/W

Note Mounted on glass epoxy board of 1 inch x 1 inch x 0.8 mm

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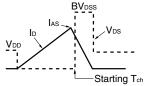


CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.0		2.5	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 10 A	12			S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 10 A		3.3	4.3	mΩ
	RDS(on)2	V _{GS} = 4.5 V, I _D = 10 A		4.1	5.6	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		6600		pF
Output Capacitance	Coss	V _{GS} = 0 V		970		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		530		pF
Turn-on Delay Time	t d(on)	V _{DD} = 15 V, I _D = 10 A		24		ns
Rise Time	t r	V _{GS} = 10 V		29		ns
Turn-off Delay Time	t d(off)	R _G = 10 Ω		130		ns
Fall Time	t _f			39		ns
Total Gate Charge	Q _G	V _{DD} = 15 V		52		nC
Gate to Source Charge	Qgs	V _{GS} = 5 V		16		nC
Gate to Drain Charge	Q _{GD}	I _D = 19 A		18		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	I _F = 19 A, V _{GS} = 0 V		0.8		٧
Reverse Recovery Time	trr	I _F = 19 A, V _{GS} = 0 V		42		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		41		nC
Gate Resistance	Rg	f = 1 MHz		1.2		Ω

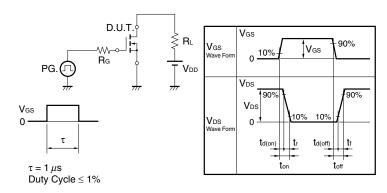
Note Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY

$\begin{array}{c} \text{D.U.T.} \\ \text{RG} = 25 \ \Omega \\ \text{VGS} = 20 \rightarrow 0 \ \text{V} \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{FG.} \\ \text{FG.} \\ \text{M.M.} \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{FG.} \\ \text{M.M.} \end{array}$



TEST CIRCUIT 2 SWITCHING TIME

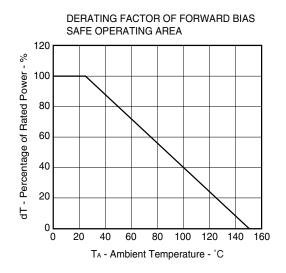


TEST CIRCUIT 3 GATE CHARGE

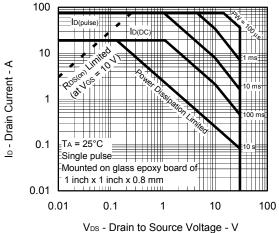
$$\begin{array}{c|c} D.U.T. \\ \hline I_G = 2 \text{ mA} \\ \hline \end{array}$$

$$\begin{array}{c|c} PG. \\ \hline \end{array} \begin{array}{c} S \\ S \\ \end{array} \begin{array}{c} S \\ S \\ \end{array} \begin{array}{c} O.U.T. \\ \hline \end{array}$$

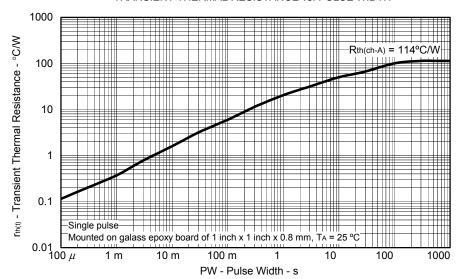
TYPICAL CHARACTERISTICS (TA = 25°C)



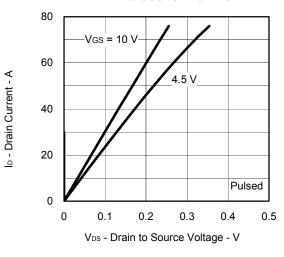
FORWARD BIAS SAFE OPERATING AREA



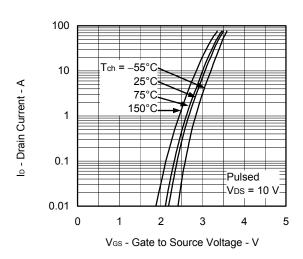
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



FORWARD TRANSFER CHARACTERISTICS



GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE 3 Ves(off) - Gate Cut-off Voltage - V 2 1 Vps = 10 V Pulsed 0 -50 0 50 100 150

100 y_{fs} | - Forward Transfer Admittance - S $T_{ch} = -55^{\circ}C$ 10 150°C VDS = 10 V

DRAIN CURRENT

0.1

0.1

0.01

FORWARD TRANSFER ADMITTANCE vs.

ID - Drain Current - A

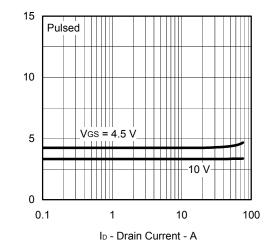
Pulsed

100

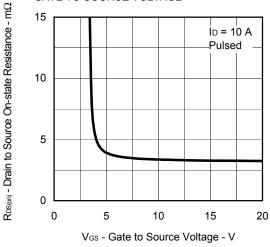
10

DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

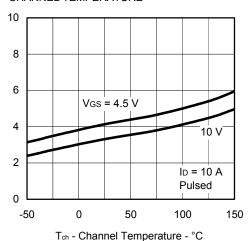
Tch - Channel Temperature - °C



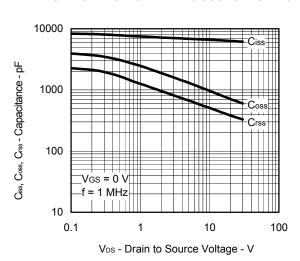
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



DRAIN TO SOURCE ON-STATE RESISTANCE vs. **CHANNEL TEMPERATURE**



CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



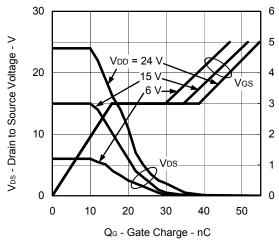
RDS(01) - Drain to Source On-state Resistance - m\Omega

R_{DS(m)} - Drain to Source On-state Resistance - mΩ

Ves - Gate to Source Voltage - V

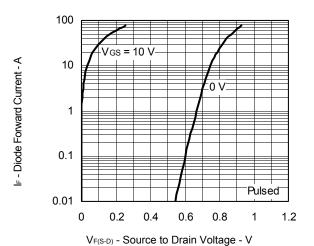
SWITCHING CHARACTERISTICS 1000 ta(on), tr, ta(off), tr - Switching Time - ns td(off) 100 td(on) 10 VDD = 15 V Vgs = 10 V $R_G = 10 \Omega$ 0.1 1 10 100

DYNAMIC INPUT/OUTPUT CHARACTERISTICS

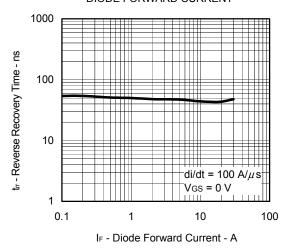


SOURCE TO DRAIN DIODE FORWARD VOLTAGE

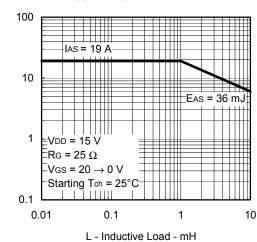
ID - Drain Current - A



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

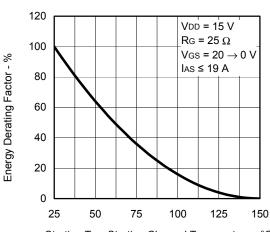


SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



IAS - Single Avalanche Current - A

SINGLE AVALANCHE ENERGY **DERATING FACTOR**

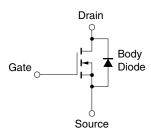


Starting Tch - Starting Channel Temperature - °C

PACKAGE DRAWING (Unit: mm)

Power SOP8 1, 2, 3 ; Source 4 ; Gate 5, 6, 7, 8 ; Drain 6.0 ±0.3 4.4 0.8 1, 2, 3 ; Source 4 ; Gate 5, 6, 7, 8 ; Drain

EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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